

II. Status of Manufacturing Process Technology

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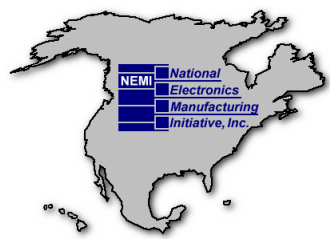
Scope and Objectives

- **Scope:** Provide the current status and issues for eliminating the six materials banned by the RoHS Directive.
- **Objectives:**
 - Demonstrate successful practices.
 - Outline sources of support and information for the conversion.
 - Identify areas requiring further work.



Scope

- **Current status of Pb-free soldering, including:**
 - **Materials (solders and lead surface finishes)**
 - **Processes (reflow, wave, repair)**
 - **Equipment**
 - **Standards**
- **Status on the elimination of other five materials banned by RoHS.**
- **Panel discussion.**



Session Agenda

- **1:00 PM** **Session scope/goals** **Bob Pfahl, NEMI**
- **1:10 PM** **State of the Pb-Free Process Technology**
 - **Reflow Soldering** **Jasbir Bath, Solectron**
 - **Rework and Repair** **Jasbir Bath, Solectron**
- **2:00 PM** **Wave Soldering: Ursula Marquez, Vitronics-Soltec**
- **2:40 PM** **Break**
- **3:00 PM** **Lead Finishes for High Reliability: Bob Hilty, Tyco**
- **3:40 PM** **Elimination of other restricted materials: Joe Johnson, Microsoft**
- **4:10 PM** **IPC Assembly Process Specifications: Frank Grano, Sanmina-SCI**
- **4:30 PM** **Panel discussion of Successful Company Programs and Future Needs: All session speakers**
- **5:00 PM** **Session Close**